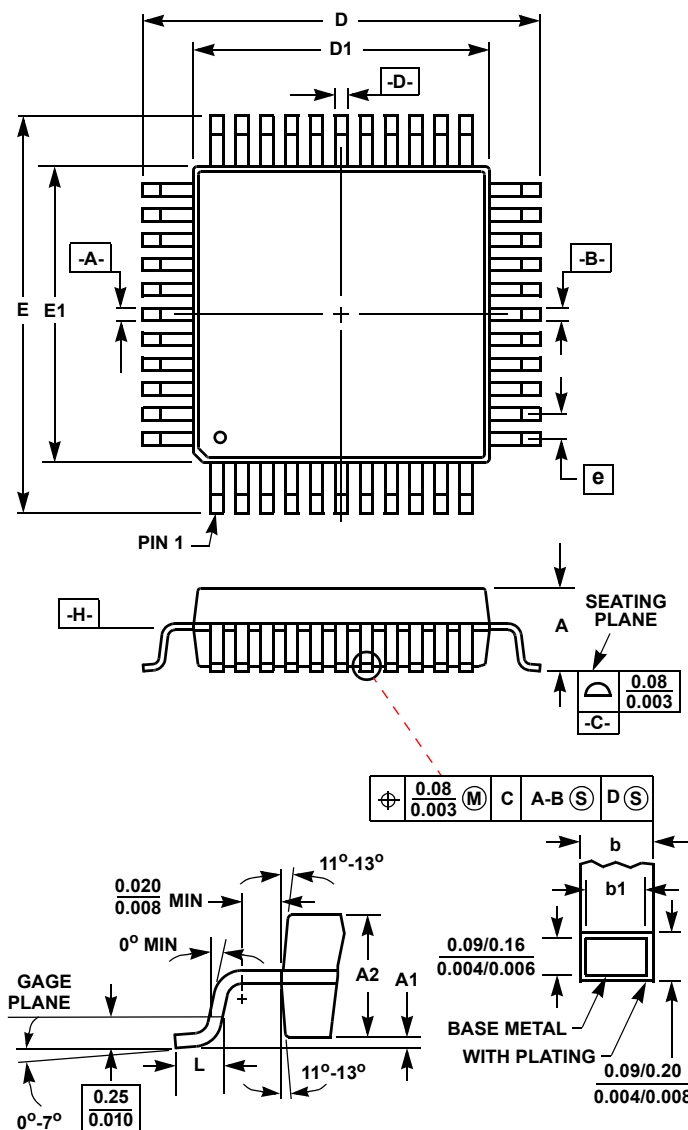


Plastic Packages for Integrated Circuits

Thin Plastic Quad Flatpack Packages (TQFP)



Q64.10x10 (JEDEC MS-026ACD ISSUE B)
64 LEAD THIN PLASTIC QUAD FLATPACK PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.047	-	1.20	-
A1	0.002	0.005	0.05	0.15	-
A2	0.038	0.041	0.95	1.05	-
b	0.007	0.010	0.17	0.27	6
b1	0.007	0.009	0.17	0.23	-
D	0.468	0.476	11.90	12.10	3
D1	0.390	0.397	9.9	10.10	4, 5
E	0.468	0.476	11.9	12.10	3
E1	0.390	0.397	9.9	10.10	4, 5
L	0.018	0.029	0.45	0.75	-
N	64		64		7
e	0.020 BSC		0.50 BSC		-

Rev. 0 7/98

NOTES:

1. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.
2. All dimensions and tolerances per ANSI Y14.5M-1982.
3. Dimensions D and E to be determined at seating plane -C-.
4. Dimensions D1 and E1 to be determined at datum plane -H-.
5. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm (0.010 inch) per side.
6. Dimension b does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum b dimension by more than 0.08mm (0.003 inch).
7. "N" is the number of terminal positions.